

64. An apparatus for processing a substrate, comprising:

a particle measuring device for measuring particles on the substrate;

an apply tool for applying a film on the substrate;

a device that automatically selects parameters for cleaning the substrate based on information about the particles obtained by the particle measuring device; and

a substrate cleaning tool for cleaning the substrate with the parameters so selected.

Remarks

Claims 2-19, 29-32, 34, and 37-64 are pending in the application. Claims 1, 20-28, 33, 35, and 36 have been canceled. Claims 37-64 have been added. No new matter has been added by virtue of this amendment. Consideration of the application as amended is requested. If there are any questions please call applicant's attorney at 802 864-1575.

Respectfully submitted,

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